

Miramid® H3KC

Polyamide 6

BASF Leuna GmbH

Message:

Miramid® H3KC is a Polyamide 6 (Nylon 6) material. It is available in Europe for injection molding.

Important attributes of Miramid® H3KC are:

Chemical Resistant

Crystalline

Fast Molding Cycle

Good Processability

Mold Release Agent

Typical applications include:

Automotive

Engineering/Industrial Parts

Electrical/Electronic Applications

Handles

General Information	
Additive	Mold Release
Features	Crystalline
	Fast Molding Cycle
	Fuel Resistant
	Good Flow
	Good Moldability
	Grease Resistant
	Oil Resistant
	Solvent Resistant
Uses	Automotive Interior Parts
	Connectors
	Engineering Parts
	Handles
	Thin-walled Parts
Forms	Granules
Processing Method	Injection Molding
Multi-Point Data	Creep Modulus vs. Time (ISO 11403-1)
	Isochronous Stress vs. Strain (ISO 11403-1)
	Isothermal Stress vs. Strain (ISO 11403-1)
	Secant Modulus vs. Strain (ISO 11403-1)
	Shear Modulus vs. Temperature (ISO 11403-1)

Physical	Dry	Conditioned	Unit	Test Method
Density	1130	--	kg/m³	ISO 1183 ¹

Melt Volume-Flow Rate (MVR) (275°C/5.0 kg)	160	--	cm ³ /10min	ISO 1133
Water Absorption				ISO 62 ²
Saturation	9.0	--	%	
Equilibrium	2.5	--	%	
Viscosity number	145	--	cm ³ /g	ISO 307, 1157, 1628 ³
Mechanical	Dry	Conditioned	Unit	Test Method
Tensile modulus	3400	1200	MPa	ISO 527-2 ⁴
Tensile Stress (Yield)	90.0	50.0	MPa	ISO 527-2 ⁵
Tensile Strain (Yield)	4.0	20	%	ISO 527-2 ⁶
Nominal Tensile Strain at Break	10	> 50	%	ISO 527-2/50
Flexural Modulus	2700	--	MPa	ISO 178
Impact	Dry	Conditioned	Unit	Test Method
Charpy notched impact strength				ISO 179/1eA ⁷
-30°C	4.50	--	kJ/m ²	
23°C	5.00	20.0	kJ/m ²	
Charpy impact strength				ISO 179/1eU ⁸
-30°C	No Break	--		
23°C	No Break	No Break		
Thermal	Dry	Conditioned	Unit	Test Method
Deflection Temperature Under Load				ISO 75-2 ⁹
0.45 MPa	190	--	°C	
1.8 MPa	65.0	--	°C	
Melting Temperature (DSC)	220	--	°C	ISO 3146
Electrical	Dry	Conditioned	Unit	Test Method
Volume resistivity	1.0E+13	1.0E+10	ohms·m	IEC 60093 ¹⁰
Dielectric Constant (1 MHz)	3.40	6.00		IEC 60250
Dissipation Factor (1 MHz)	0.015	0.25		IEC 60250 ¹¹
Comparative tracking index	600	--		IEC 60112 ¹²
Injection	Dry	Unit		
Processing (Melt) Temp	240 to 270		°C	
Mold Temperature	80.0 to 120		°C	
NOTE				

1.

Tested in accordance with ISO 10350. 23°C/50%r.h. unless otherwise noted.

2.

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3.

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4.	Tested in accordance with ISO 10350. 23°C/50%r.h. unless otherwise noted.
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10.	Tested in accordance with ISO 10350. 23°C/50%r.h. unless otherwise noted.
11.	Tested in accordance with ISO 10350. 23°C/50%r.h. unless otherwise noted.
12.	Tested in accordance with ISO 10350. 23°C/50%r.h. unless otherwise noted.

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